

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6005538

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUN-WEN CHENG	11/24/2017
CHIA-HUA CHU	11/23/2017
CHUN-YIN TSAI	11/23/2017
TZU-HENG WU	11/23/2017
WEN-CHENG KUO	11/23/2017
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD
Street Address:	NO. 8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16813923
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	252011-6941
NAME OF SUBMITTER:	DANIEL R. MCCLURE
SIGNATURE:	/Daniel R. McClure/
DATE SIGNED:	03/10/2020
Total Attachments: 2	

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ASSIGNMENT

WHEREAS, Chun-Wen CHENG, Chia-Hua CHU, Chun-Yin TSAI, and Tzu-Heng WU, Wen-Cheng KUO

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: INTEGRATED MICROPHONE DEVICE AND MANUFACTURING METHOD THEREOF

Filed: 2017-10-30

Serial No. 15/797,813

Executed on: _____

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2017/11/24 Chun-Wen Cheng
Date Name: Chun-Wen CHENG

2017/11/23 Chia-Hua Chu
Date Name: Chia-Hua CHU

2017/11/23 Chun-Yin Tsal
Date Name: Chun-Yin TSAI

2017/11/23 Tzu-Heng Wu
Date Name: Tzu-Heng WU

2017/11/23 Wen-Cheng Kuo
Date Name: Wen-Cheng KUO